



## SSC8429GN6

### P-Channel Enhancement Mode MOSFET

#### ➤ Features

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
-20V	$\pm 12V$	4m $\Omega$ @-4V5	-90A
		6m $\Omega$ @-2V5	

#### ➤ Description

This SSC8429GN6 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

**100% UIS +  $\Delta V_{DS}$  +  $R_g$  Tested!**

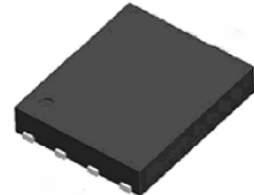
#### ➤ Applications

- Load Switch
- PWM Application
- Power Management

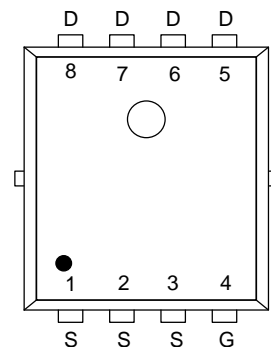
#### ➤ Ordering Information

Device	Package	Shipping
SSC8429GN6	PDFN5X6-8L	5000/Reel

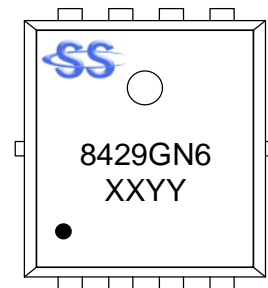
#### ➤ Pin configuration



**PDFN5X6-8L (Top View)**



**Pin Configuration**



**Marking**

(XXYY: Internal Traceability Code)



### ➤ Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	-20	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current <sup>d</sup>	$T_C=25^{\circ}\text{C}$	-90
		$T_C=100^{\circ}\text{C}$	-48
$I_{DSM}$	Continuous Drain Current <sup>a</sup>	$T_A=25^{\circ}\text{C}$	-27
		$T_A=70^{\circ}\text{C}$	-20
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	-360	A
$P_D$	Power Dissipation <sup>c</sup>	$T_C=25^{\circ}\text{C}$	52
		$T_C=100^{\circ}\text{C}$	21
$P_{DSM}$	Power Dissipation <sup>a</sup>	$T_A=25^{\circ}\text{C}$	4.8
		$T_A=70^{\circ}\text{C}$	3
$I_{AS}$	Avalanche Current <sup>b</sup> $L=0.5\text{mH}$ Single Pulse	-34	A
$E_{AS}$	Avalanche Energy <sup>b</sup> $L=0.5\text{mH}$ Single Pulse	289	mJ
$T_J$	Operation junction temperature	-55~150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55~150	

### ➤ Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	26	33	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	2.4	3.1	

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The power dissipation is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

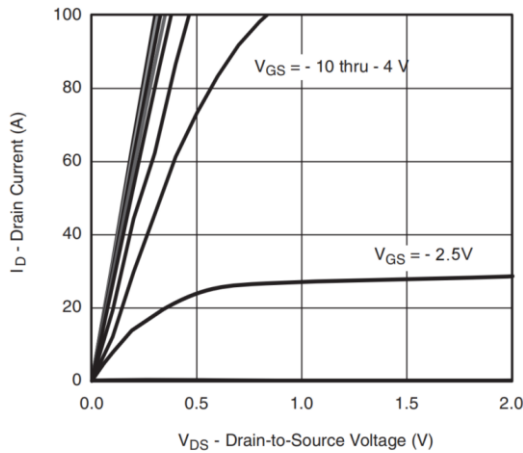


➤ **Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

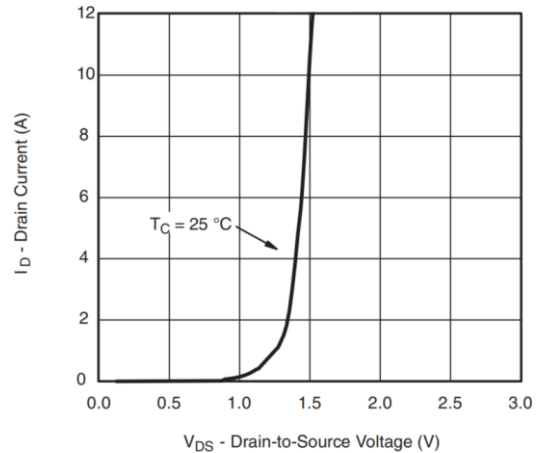
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-0.5	-0.7	-1	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -15A		4	7	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -10A		6	9	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -10A		48		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -10A		-0.7	-1.3	V
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, f = 1MHz		1.8		Ω
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1MHz		3712		pF
Output Capacitance	C <sub>OSS</sub>			465		
Reverse Transfer Capacitance	C <sub>RSS</sub>			368		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -20A		25		nC
Gate to Source Charge	Q <sub>GS</sub>			6.5		
Gate to Drain Charge	Q <sub>GD</sub>			8.5		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, R <sub>L</sub> = 2Ω, R <sub>G</sub> = 3Ω		18		ns
Rise Time	T <sub>r</sub>			12		
Turn-off Delay Time	T <sub>D(OFF)</sub>			36		
Fall Time	T <sub>f</sub>			9		



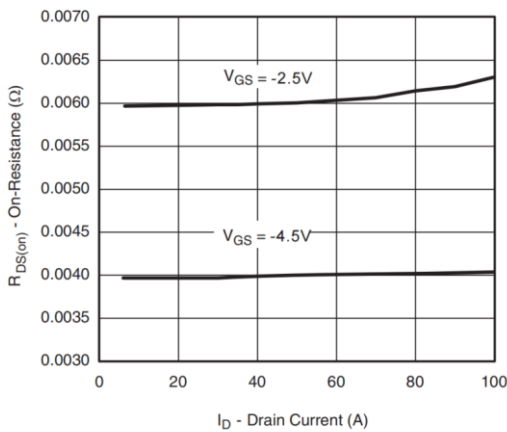
➤ **Typical Performance Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**



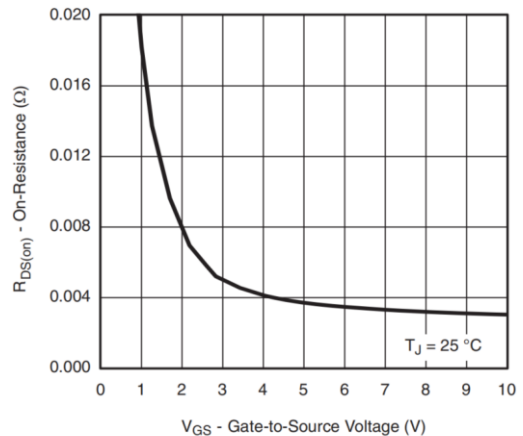
**Output Characteristics**



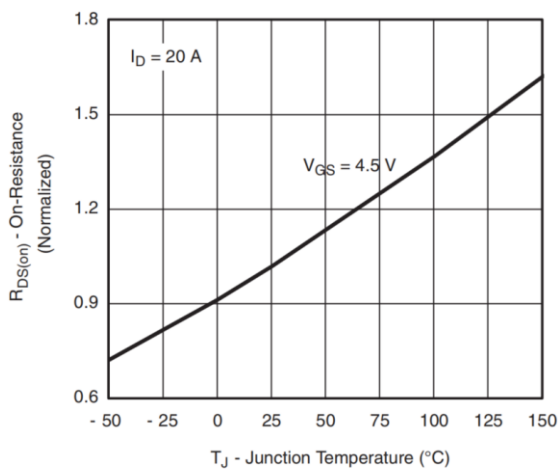
**Transfer Characteristics**



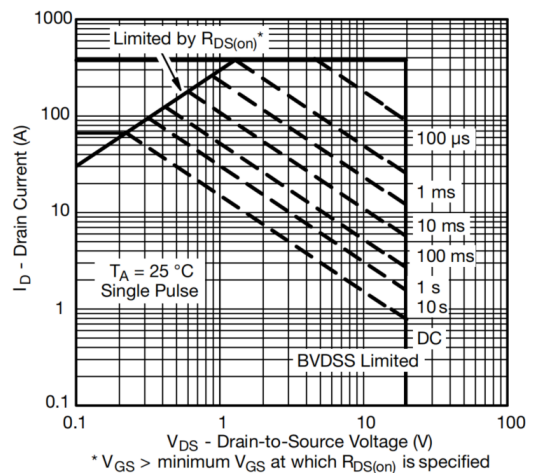
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**

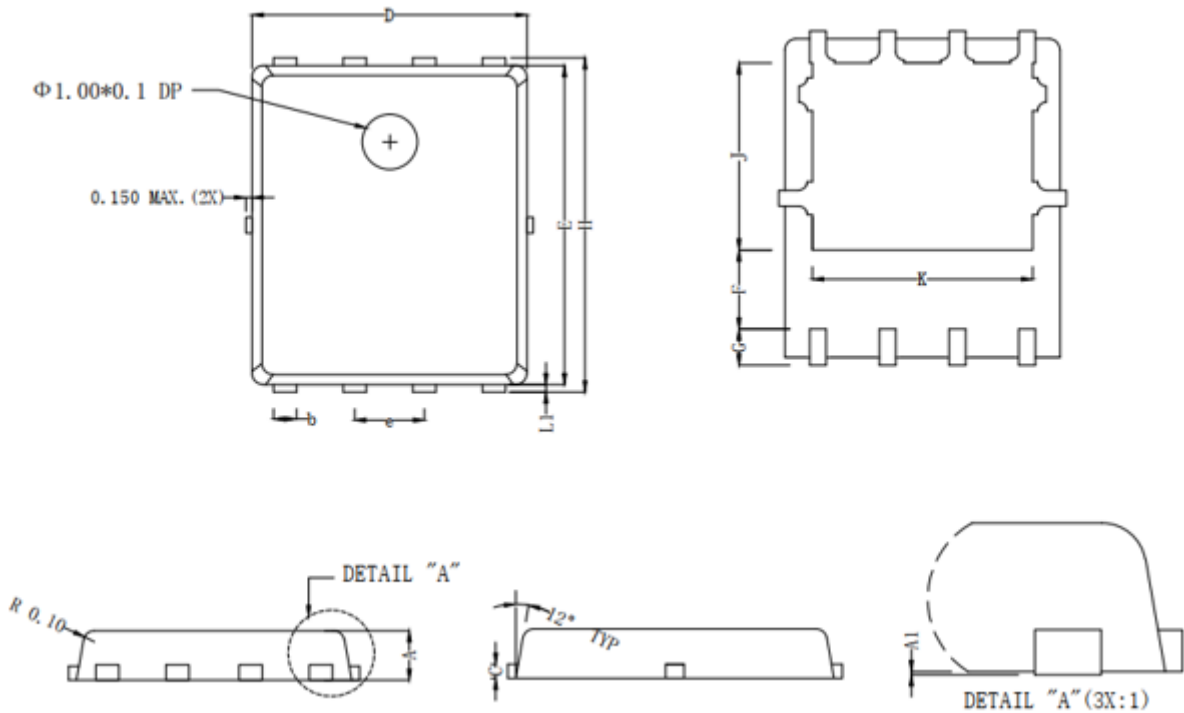


**On-Resistance vs. Junction Temperature**



**Safe Operating Area, Junction-to-Ambient**

## ➤ Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.90	1.00	1.10
A1	0.00	0.03	0.05
b	0.25	0.03	0.35
c	0.254 REF		
D	4.80	4.90	5.00
F	1.35 REF		
E	5.65	5.75	5.85
e	1.27 BSC		
H	5.90	6.00	6.10
L1	0.10	0.13	0.16
G	0.55 REF		
K	4.00 REF		
J	3.45 REF		



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